

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 1, line 19, with the following rewritten paragraph:

1 As an example, an integrated circuit ~~a specific ASP Wireless device~~
2 containing an Analog to Digital Converter (ADC) typically requires test
3 verification. The test verification of two key parameters F(full scale)set and
4 Z(zero)set is usually considered ~~are critical in such cases~~. Unfortunately, contact
5 resistance during bump probing is often too high to correctly validate the
6 operation of the ADC for these two parameters.

IN THE ABSTRACT:

Please replace the paragraph beginning at page 19, line 4, with the following rewritten paragraph:

1 Apparatus and methods for testing conductive bumps or target test points
2 on integrated circuits, comprising A ~~a multiplicity of probes~~ are extended
3 ~~extending through a support substrate~~. At least one of the multiplicity of probe
4 locations include ~~including~~ a second electrically isolated probe such that the test
5 point is in contact with two probes. One of the two probes provides ~~providing~~ a
6 voltage to the test point and the second probe sensing the voltage so as to
7 provide a Kelvin connection.